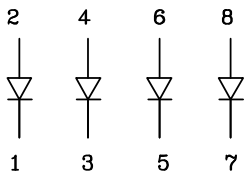
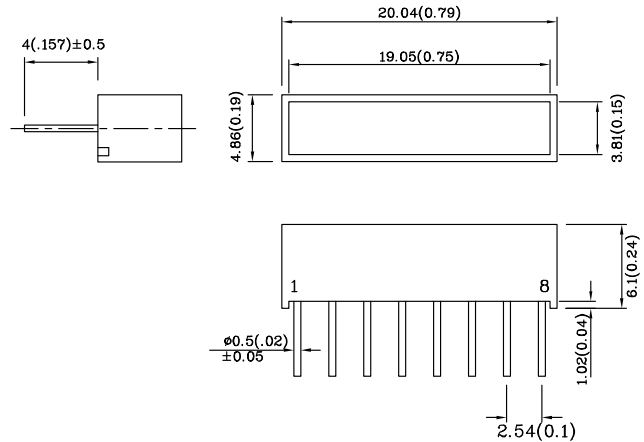


Features

- UNIFORM LIGHT EMITTING AREA.
- LOW CURRENT OPERATION.
- EASILY MOUNTED ON P.C. BOARDS.
- FLUSH MOUNTABLE.
- CAN BE USED WITH PANELS AND LEGEND MOUNTS.
- EXCELLENT ON/OFF CONTRAST.
- RoHS COMPLIANT.



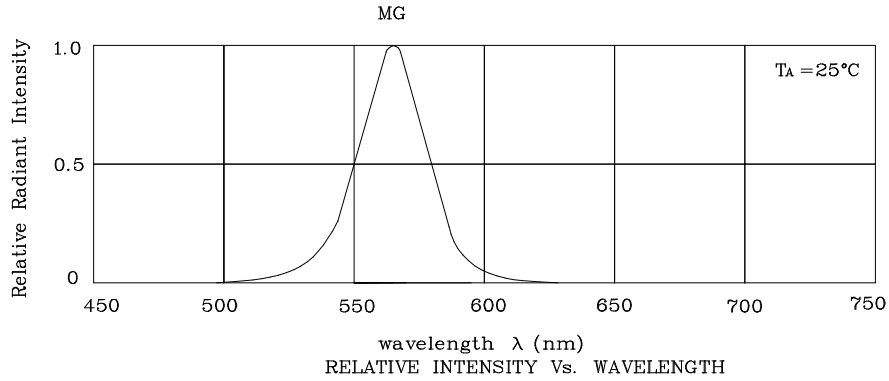
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.

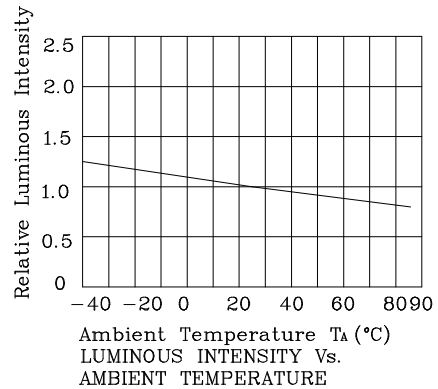
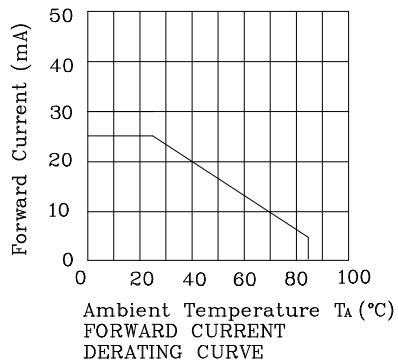
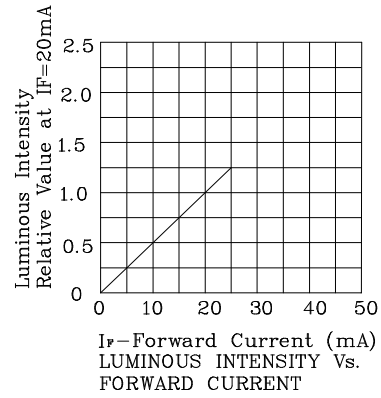
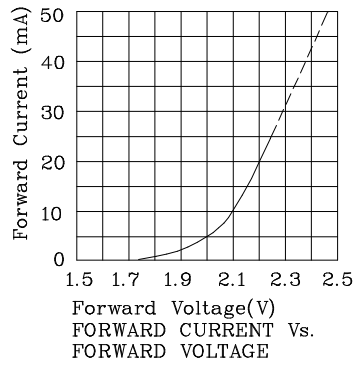
Absolute Maximum Ratings (TA=25°C)		MG (GaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	PT	105	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		MG (GaP)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	2.2	V
Forward Voltage (Max.) (IF=20mA)	VF	2.5	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=20mA)	λP	565	nm
Wavelength of Dominant Emission (IF=20mA)	λD	568	nm
Spectral Line Full Width At Half-Maximum (IF=20mA)	$\Delta\lambda$	30	nm
Capacitance (VF=0V, f=1MHz)	C	15	pF

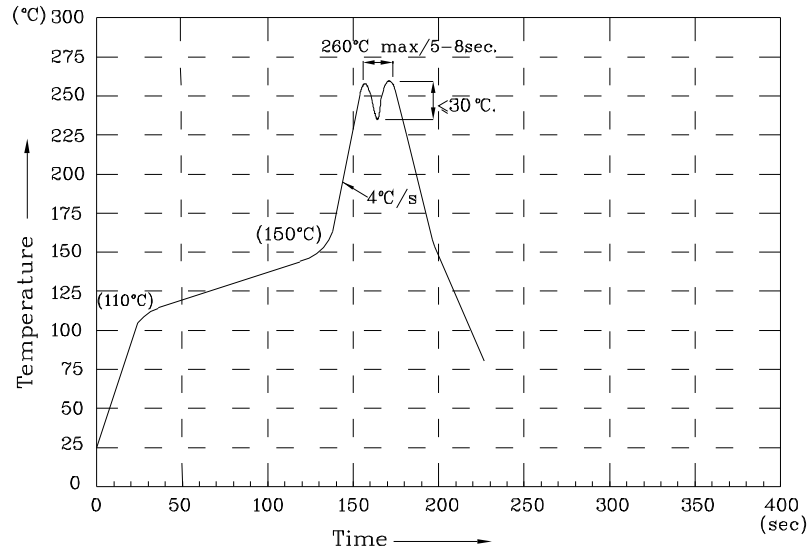
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λP
				min.	typ.	
XEMG2550D	Green	GaP	Green Diffused	18	69	565



❖ MG



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.